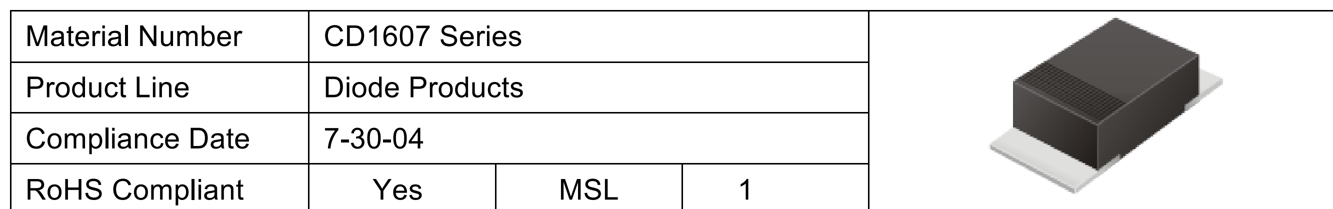
MATERIAL DECLARATION SHEET



Material Number	CD1607 Series		
Product Line	Diode Products		
Compliance Date	7-30-04		
RoHS Compliant	Yes	MSL	1

No.	Construction Element (subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material / Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Lead Frame	Alloy	0.0102	Copper	7440-50-8	97.05%	57.26	58.62
				Iron	7439-89-6	2.6%	1.53	
				Phosphorus	7723-14-0	0.15%	0.09	
				Zinc	7440-66-6	0.2%	0.12	
2	Chip	Dice	0.0001	Silicon	7440-21-3	97.6%	0.59	0.575
				Gold	7440-57-5	0.8%	0.00	
				Aluminum	7429-90-5	0.8%	0.00	
				Nickel	7440-02-0	0.8%	0.00	
				Impurity	---	0.5%	0.00	
3	Solder	Pb/Sn/Ag High Temp Solder	0.0001	Tin	7440-31-5	5%	0.04	0.575
				Lead	7439-92-1	92.5%	0.65	
				Silver	7440-22-4	2.5%	0.02	
4	Molding Compound	Epoxy	0.0069	Silica (Fused)	60676-86-0	80%	31.20	39.655
				Epoxy Resin	29690-82-2	11.5%	4.49	
				Phenolic Resin	9003-35-4	6%	2.34	
				Mixed Siloxanes	2530-83-8	2%	0.78	
				Carbon Black	1333-86-4	0.5%	0.20	
5	Plating	Tin	0.0001	Tin	7440-31-5	100%	0.70	0.575
		Total weight	0.0174					

This Document was updated on: 11 July 2013

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.

1. 7(a) – Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead).

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